

ICTA 2020 Organizing Committee

General Co-Chairs:

Zhihua Wang, *Tsinghua, China*

Xiaohu You, *Southeast U., China*

Steering Committee Chair:

Fujiang Lin, *USTC, China*

TPC Co-Chairs:

Liyuan Liu, *IS-CAS, China*

Dixian Zhao, *Southeast U., China*

International Advisors:

Jan Van der Spiegel, *U. Penn, USA*

Christian Enz, *EPFL, Switzerland*

Yann Deval, *U. Bordeaux, France*

Hoi-Jun Yoo, *KAIST, Korea*

Yong Lian, *IEEE CASS, USA*

Ke Wu, *IEEE MTT-S, Canada*

Albert Wang, *IEEE EDS, USA*

Makoto Ikeda, *U. of Tokyo, Japan*

James Hwang, *Lehigh U. USA*

Local Arrangement Chair:

Jun Yang, *Southeast U., China*

Invited Program Chair:

Zhiqun Li, *Southeast U., China*

Tutorial Chair:

Nanjian Wu, *IS-CAS, China*

Keynote Speakers Chair:

Lin Cheng, *USTC, China*

Industry Papers Chair:

Hongtao Xu, *Fudan U., China*

Student Papers Chair:

Xian Tang, *Tsinghua, China*

Program/Sessions Chair:

Weiwei Shan, *SEU, China*

Awards Committee Chair:

Zheng Wang, *UESTC, China*

Publication/Booklet Chair:

Nanjian Wu, *IS-CAS, China*

Submission Website Chair:

Qing Wu, *BIE, China*

Finance Chair:

Ying Zhang, *BIE, China*

Sponsorship/Exhibition Chair

Weiwei Shan, *Southeast U., China*

Conference Manager:

Xing Zhang, *BIE, China*

TPC Members (Up-to-date):**1. RFIC and MMIC****Co-Chair:**

Zhao Bo, *Zhejiang University, China*

Wang Zheng, *UESTC, China*

Members:

Bi Xiaojun, *HUST, China*

Li Ning, *Sophia University, Japan*

Feng Haigang, *Tsinghua Shenzhen Institute, China*

Meng Xu, *Heifei U. of Technology, China*

Zhu Xi, *U. of Technology Sydney, Australia*

Deng Wei, *Tsinghua University, China*

Yan Na, *Fudan, China*

Wu Rui, *IE, CAS, China*

Yin Jun, *University of Macau, China*

Wang Keping, *Tianjing University, China*

Jia Haikun, *Tsinghua University, China*

Gao Xiang, *Zhejiang University, China*

Zhang Gang, *Tongji University, China*

Diao Xisheng, *East China Normal University, China*

Yang Shiheng, *UESTC, China*

2. Analog and Mixed-Signal ICs**Co-Chair:**

Sin Sai-Weng, *University of Macau, China*

Li Qiang, *UESTC, China*

Members:

Chen Zhijie, *Beijing U of Tech., China*

Cheng lin, *USTC, China*

Guo Jianping, *Sun Yat-sen University, China*

Liu Jiabin, *Tsinghua University, China*

Lu Yan, *University of Macau, China*

Luo Yuxuan, *Zhejiang University, China*

Qu Wanyuan, *Zhejiang University, China*

Tang Xian, *Tsinghua University Shenzhen, China*

Zhan Chenchang, *SUSTC, China*

Zhou Xiong, *UESTC, China*

3. Digital ICs**Co-Chair:**

Yu Zhiyi, *Sun Yat-Sen University, China*

Zhou Jun, *UESTC, China*

Members:

Yin Shouyi, *Tsinghua, China*

Shan Weiwei, *Southeast University, China*

Fan Youzhe, *MaxLinear Inc. USA*

Wang Chao, *HUST, China*

Xu Ke, *ZTE, China*

Lin Jun, *Nan Jing University, China*

Li Lin, *Hisilicon, China*

An Fengwei, *SUSTech, China*

Xiao Shanlin, *Sun Yat-Sen University, China*

Shi Cong, *Chongqing University, China*

4. Wireline ICs**Co-Chair:**

Qi Nan, *IS CAS, China*

Zhang Feng, *IMECAS, China*

Members:

Pan Quan, *SUSTech, China*

Zhang Zhao, *Japan*

Wang Binhao, *HP Labs, USA*
Li Dan, *XJTU, China*
Zheng Xuqiang, *IMECAS, China*
Chen Yong, *Macau U., China*

Gui Xiaoyan, *XJTU, China*
Tan Min, *HUST, China*
Wang Ziqiang, *Tsinghua U. , China*

5. Modeling, CAD and Testing

Co-Chair:

Xu Yuehang, *UESTC, China*

Members:

Liu Jun, *HDU, China*
Li Ling, *IME, CAS, China*
Yongxin Guo, *NUS, SINGAPORE*
Crupi Giovanni, *University of Messina, Italy*

Lv Kai, *IME, CAS, Singapore*
Wu Yunqiu, *UESTC, China*
Chen Peng, *Cardiff University, UK*

6. Device and Process Technologies

Co-Chair:

Wang Xingsheng, *HUST, China*

Members:

Chen Jiezhi, *Shangdong Univ., China*
Wan Jing, *Fudan University, China*
Gao Bin, *Tsinghua University, China*
Chen Rongmei, *Imec, Belgium*
Wang Runsheng, *Peking University, China*

Li Yi, *HUST, China*
Gao Bin, *Tsinghua University , China*
Wang Hong, *Xidian University, China*
Cheng Binjie, *Synopsys, UK*

7. Packaging and Hybrid Integration

Co-Chair:

Shang Jintang, *Southeast University, China*

Members:

Wang Jun, *Fudan University, China*
Wang Qidong, *IMCAS, China*
Yu Daquan, *Xiamen University, China*
Cui Chengqiang, *GDUT, China*
Miao Min, *BISTU, China*
Sun Ligu, *USTC, China*

Hang Tao, *Shanghai Jiaotong University, China*

Wang Chenxi, *Harbin Institute of Technology, China*
Liu Yingxia, *BIT, China*
Cai Jian, *Tsinghua University, China*
Wei Xingchang, *Zhejiang University, China*
Sun Sheng, *UESTC, China*
Wu Rongxiang, *UESTC, China*

8. Sensors and Applications

Co-Chair:

Yu Hao, *SUSTech, China*

Members:

Yu Guoyi, *HUST, China*
An Fengwei, *SUSTech, China*
Liu Xu, *Beijing University of Technology, China*
Li Yongfu, *Shanghai Jiao Tong University, China*
Feng Peng, *ISCAS, China*

Chen Quan, *The University of Hong Kong*
Qi Gengzhen, *Institute of microelectronics*
Huang Xiwei, *Hangzhou Dianzi University, China*
Deepu John, *University College Dublin, Ireland*

9. IC Based Applications

Co-Chair:

Chen Zihao, *HIT, China*

Members:

Wang Kaixu, *HIT (Shenzhen), China*

Zhang Bing, *Sichuan University, China*
Wang Junjun, *Beihang University, China*
Xu Sha, *GDUT, China*
Yang Yongkui, *SIAT, CAS, China*

Zhu Xi, *U. of Technology Sydney, Australia*
Zhu Haoshen, *SCUTech, China*
Chen Zhuozhu, *GDUT, China*
Wang Zheng, *SIAT, CAS, China*

10. Emerging Technologies and Applications

Co-Chair:

Sun Haiding, *USTC, China*

Members:

Tao Li, *Southeast University, China*
Li Mengmeng, *IME, CAS, China*
Wang Kai, *SUSTech, China*

Lang Jiang, *IC CAS, China*
Liao Zhaoliang, *USTC, China*
Zhou Hong, *Xidian University, China*